**Product / Process Change Notice**

**Parts Affected:**

Chip process CPD66X, switching diodes, wafers and bare die

**Extent of Change:**

The CPD66X has been modified from an Sb (antimony) dopant to an As (arsenic) dopant. There are no resultant physical changes to die size or metallization.

**Reason for Change:**

The dopant material was changed in order to enhance typical forward voltage (VF) performance and, hence, reduce forward conduction losses.

**Effect of Change:**

The wafer process meets all electrical specifications of the individual devices listed on the following page.

**Qualification:**

|  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- |
|  |  | P/N: | CPD66X Process using As |  | Package: | SOD-123 |
|  |  |  |  |  |  |  |
| **No.** | | **Test** | **Conditions** (Reference standards are in bold) | **Qty** | **Pass/Fail** | **Test Results** |
| **1** | | **Device Life Tests** | | | | |
|  | a | **High Temperature Reverse Bias (HTRB)** | T=125°C, t = 1000 hours Bias conditions per device datasheet **JESD22-A108** | 77 | Pass | 77/77 |
|  | b | **Intermittent Operational Load Life** | T=125°C, t = 1000 hours **JESD22-A108** | 22 | Pass | 22/22 |

**Effective Date of Change:**

Effective Immediately.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Part Numbers Affected:**

|  |  |
| --- | --- |
| CBAS17 | CEN1221 |
| CEN1230 | CEN1235 |
| CEN1344 | CMDD3003 |
| CMHD3595 | CMHD457A |
| CMHD459A | CMKD3003DO |
| CMLD3003DO | CMLD3003DOG |
| CMOD3003 | CMOD3003G |
| CMPD3003 | CMPD3003A |
| CMPD3003C | CMPD3003S |
| CMXD3003TO | CPD66X-CLL459A-WN |
| CPD66X-CMHD459A-WN | CPD66X-CMPD3003-CT |
| CPD66X-CMPD3003-WN | CPD66X-1N3595-WN |
| CPD66X-1N3595-WR | CPD66X-1N457A-CT |
| CPD66X-1N457A-WN | CPD66X-1N485B-CT |
| CPD66X-1N485B-WN |  |

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

|  |  |
| --- | --- |
| Company Name: |  |
| Address: |  |
|  |
|  |
| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |